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Verfahren zur Herstellung eines SOI-Wafers

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(73) Proprietor: **Shin-Etsu Chemical Co., Ltd.**
Tokyo 100-0004 (JP)

(72) Inventors:
• **Akiyama, Shoji**
Annaka-shi
Gunma-ken (JP)
• **Kubota, Yoshihiro**
Annaka-shi
Gunma-ken (JP)
• **Ito, Atsuo**
Annaka-shi
Gunma-ken (JP)

• **Tanaka, Koichi**
Annaka-shi
Gunma-ken (JP)
• **Kawai, Makoto**
Annaka-shi
Gunma-ken (JP)
• **Tobisaka, Yuuji**
Annaka-shi
Gunma-ken (JP)

(74) Representative: **Wibbelmann, Jobst**
Wuesthoff & Wuesthoff
Patent- und Rechtsanwälte
Schweigerstrasse 2
81541 München (DE)

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